

T-M8.4

Wire Bond Globe Top Package
For Dual Interface application (Controller)

Short Product Overview

May 2010

Chip Card & Security

T-M8.4 Short Product Overview		Ref.: Chip_Card_Product_Overview_11/09
Revision History: Current Version 05.10		
Previous Releases:		
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Important: Further information is confidential and on request. Please contact:
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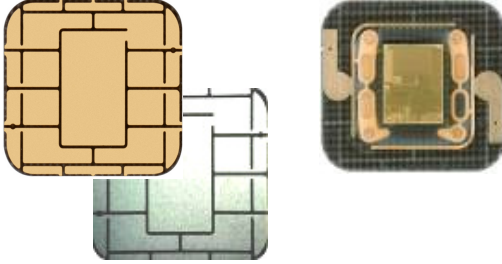
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Product name P-FTM8-2-1	T-M8.4
Picture	
Product description	Dual Interface Module 8 contacts CB 2 Antenna Contacts Epoxy Tape Wire Bond Glob Top
Typical Applications	Payment, EMV SDA/DDA, ePurse, Loyalty, Access Control, Driver Licence, Transport
Pitch	14.25 mm
Dimensions	13 x 11.8 mm
Thickness	max. 580µm
Contact Surface	NiAu / NiAuPd
Delivery form	Tape on Reel Reel diameter 330mm
ISO - reference	ISO/IEC 7810 SO/IEC 7816-1 ISO/IEC 10373-1 / -3
Derivatives	T-M8.4-8-1, Au surface T-M8.4-8-2, Pd surface T-M8.4-8-8, La/Lb to C4/C8

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